



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# LNJ937W8CRA

## High Bright Surface Mounting Chip LED

ESS II Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	40	mW
Forward current	$I_F$	10	mA
Pulse forward current *	$I_{FP}$	55	mA
Reverse voltage	$V_R$	5	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Lighting Color

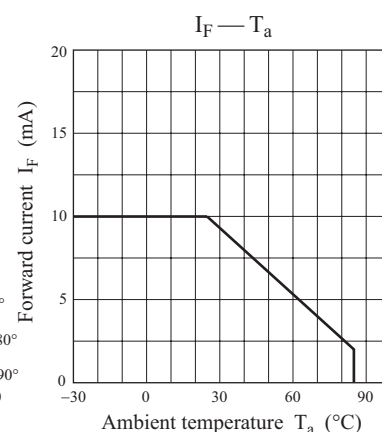
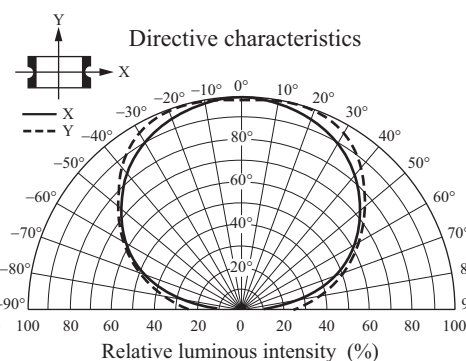
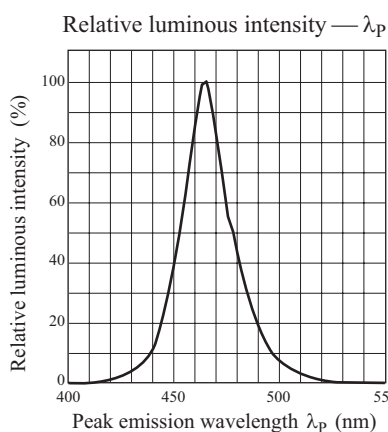
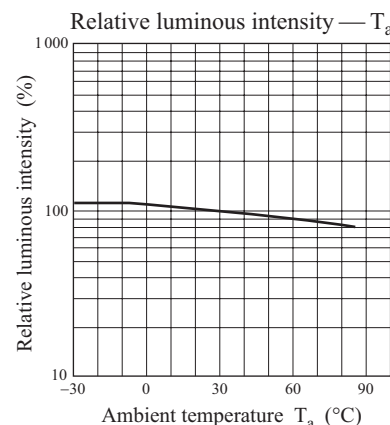
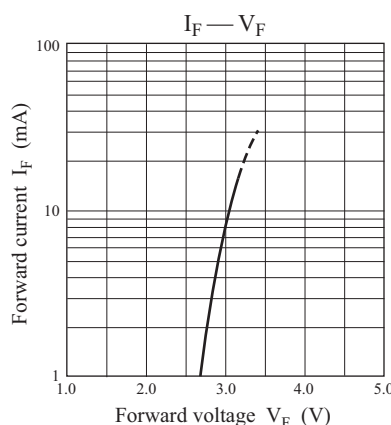
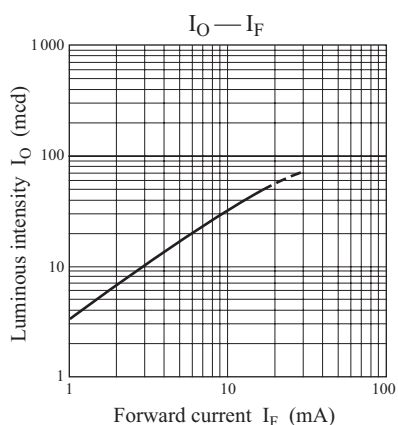
- Blue

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

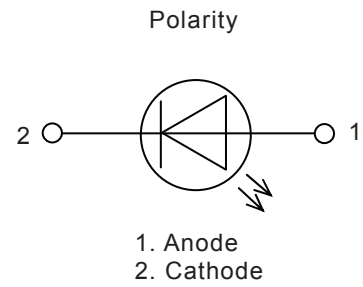
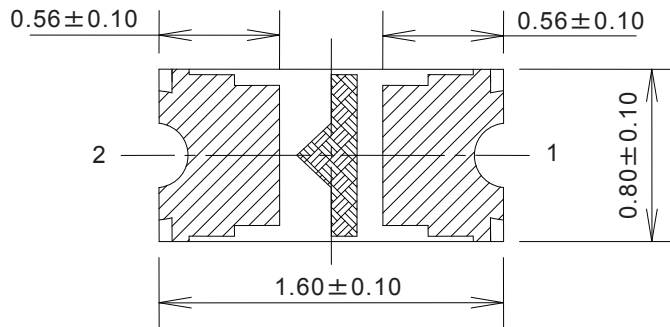
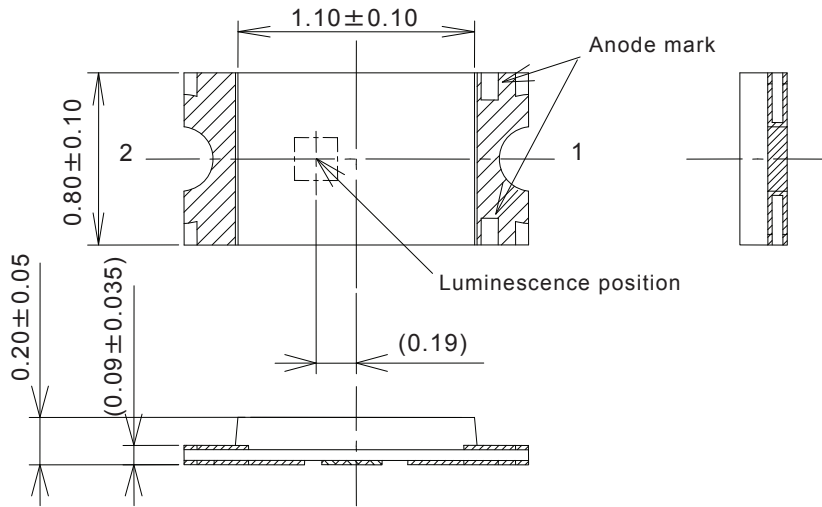
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	$I_O$	$I_F = 5\text{ mA}$	10.0	17.0	30.0	mcd
Reverse current	$I_R$	$V_R = 5\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 5\text{ mA}$		2.9	3.2	V
Peak emission wavelength	$\lambda_p$	$I_F = 5\text{ mA}$		465		nm
Dominant emission wavelength *2	$\lambda_d$	$I_F = 5\text{ mA}$	462	472	478	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5\text{ mA}$		20		nm

Note) \*1: Measurement tolerance:  $\pm 20\%$

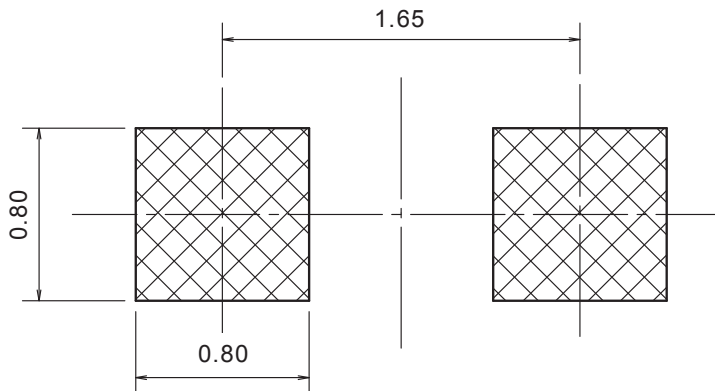
\*2: Measurement tolerance:  $\pm 2\text{ nm}$



■ Package (Unit: mm)



**Recommended Land Layout**



(Note1) Electrode projection is not included in the package dimensions.

(Note2) About solder thickness, please examine the products yourself completely.

(Recommended thickness :  $t=0.10$  mm~ $0.15$  mm)

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